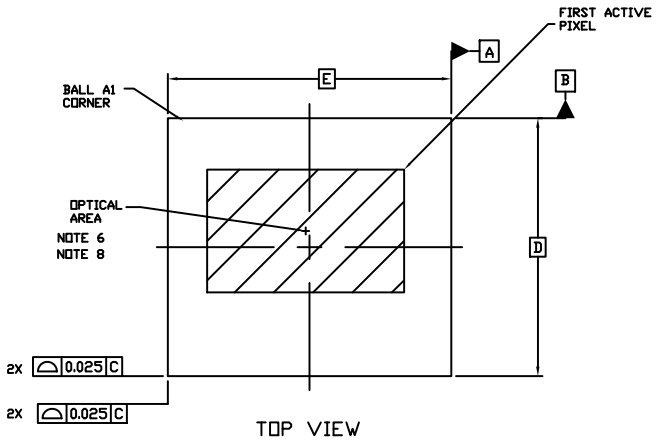
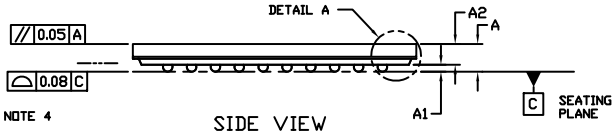
ODCSP89 8.914x8.114
CASE 570CE
ISSUE A

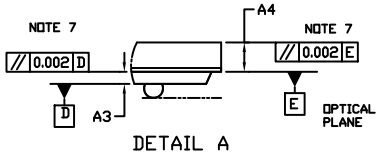
DATE 15 AUG 2017



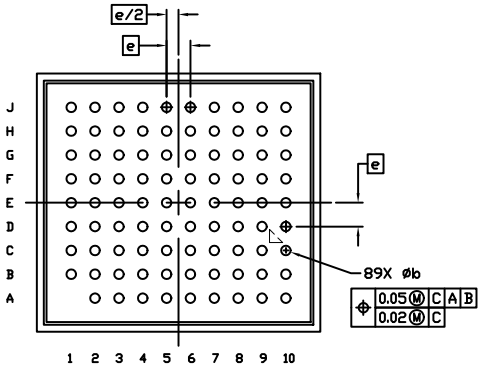
TOP VIEW



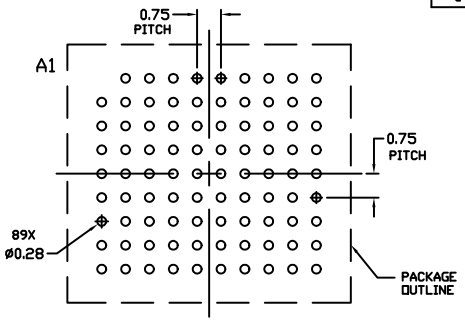
SIDE VIEW



DETAIL A



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 0.1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=−121.6 MICRONS, Y=510.11 MICRONS ±25 MICRONS.

	MILLIMETERS	
DIM	MIN.	MAX.
A	---	0.95
A1	0.19	0.25
A2	0.65 REF	
A3	0.182	0.232
A4	0.424	0.464
b	0.27	0.33
D	8.114 BSC	
E	8.914 BSC	
e	0.75 BSC	

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY M. FORBIS.	08 AUG 2017
A	CORRECTED DIMENSIONS D & E VALUES. REQ. BY M. FORBIS.	15 AUG 2017